

METHOD AND APPARATUS FOR SINGULATING SEMICONDUCTOR
PACKAGES ON A LEAD FRAME

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ABSTRACT

The present invention provides a sawing jig (230), which
comprises a first metal plate (240) having a pattern of openings (242)
for receiving packaged devices (210) on a leadframe (205), a second
10 metal plate (260) having a corresponding pattern of vacuum openings
(262), and a rubber sheet (250) held between the first and second
metal plates (240 and 260), having tubular protruding portions (252),
with ends (253) that are shaped to deform, to provide a pneumatic
seal around each of the packaged devices (210) that are held by a
15 vacuum in the openings (242) of the first metal plate (240).

FIG. 3 accompanies the abstract.



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